

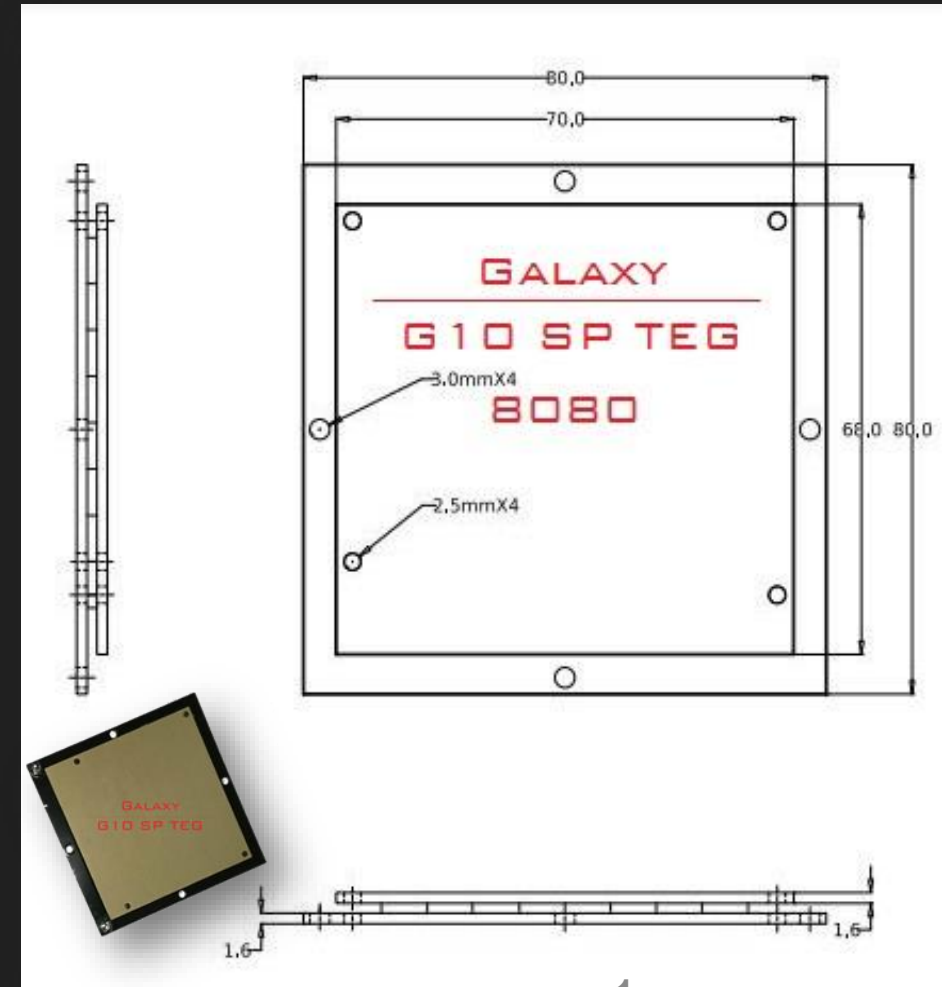
超導鋁DLC-MCPCB溫差發電片之設計(1/2)

DLC-MCPCB TEG DESIGN (1/2)

1.超導鋁DLC-MCPCB溫差發電片GALAXY G10 SP TEG SPECIFICATION 設計規格標準

DLC-MCPCB Aluminium Thermoelectric Generator Power Chip

Type	Unit	Value
G10 SP-8080		
Resistance	Ω	1.00~1.20
Working Temperature	$^{\circ}\text{C}$	-40~150
Working Humidity	RH	10~70
Storage Temperature	$^{\circ}\text{C}$	-40~50
Storage Humidity	RH	10~70
Hot Side dimension	MM	70*68
Cold Side dimension	MM	80*80
Thickness	MM	5
Wight	g	63
Pressure Load	N/cm^2	8.5
Hole Size	ψmm	$\psi 3.0\text{mm} * 6\text{E}$



超導鋁DLC-MCPCB溫差發電片之設計(2/2)

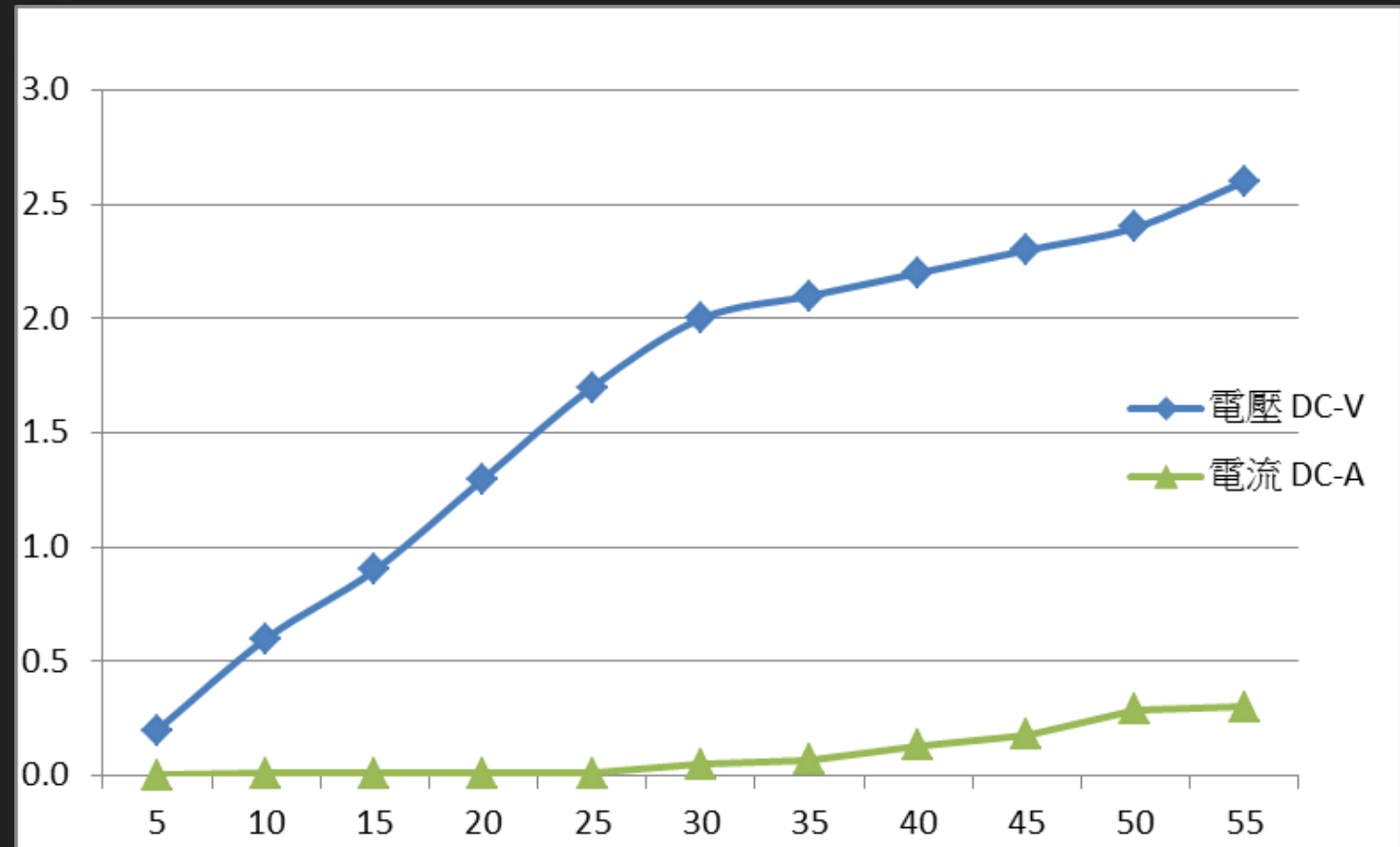
DLC-MCPCB TEG DESIGN (2/2)

2.超導鋁DLC-MCPCB溫差發電片GALAXY G10 SP

TEG SPECIFICATION 效能分析 PERFORMANCE

溫差發電效能參數 Data

溫差 $\Delta T^{\circ}\text{C}$	電壓 DC-V	電流 DC-A
5	0.2	0.0005
10	0.6	0.0100
15	0.9	0.0100
20	1.3	0.0100
25	1.7	0.0100
30	2.0	0.0500
35	2.1	0.0700
40	2.2	0.1300
45	2.3	0.1800
50	2.4	0.2900
55	2.6	0.3000



超導鋁DLC-MCPCB溫差發電標準模組1(3/3)

DLC-MCPCB TEG Module

3. 溫差發電標準模組之溫差發電效能參數分析 Module Data

溫差發電效能參數 Data

溫差 $\Delta^{\circ}\text{C}$	電壓 DC-V	電流 DC-A
5	8.1	0.1
10	12.2	0.2
15	18.3	0.4
20	20.3	0.6
25	24.4	0.7
30	30.5	1.0
35	32.5	1.2
40	40.6	1.4
45	42.6	1.5
50	46.7	1.8
55	48.7	2.1
60	52.8	2.3
65	58.9	2.5
70	62.9	2.8

